

ABSTRACT

An object of the present invention is to provide a photosensitive composition capable of suppressing residues after development, to provide a photosensitive composition capable of obtaining a cured product included in a display device having excellent light emission characteristics capable of low voltage driving in obtaining a desired current density and excellent reliability of a light emitting element, and to provide a photosensitive composition capable of obtaining a cured product included in an electronic component excellent in migration resistance. There is provided a resin being one or more resins selected from the group consisting of a polyimide, a polyimide precursor, a polybenzoxazole, a polybenzoxazole precursor, a polyamideimide, a polyamideimide precursor, and a copolymer thereof, in which the resin has a first amine residue (DA1): an amine residue having a phenolic hydroxyl group, the first amine residue (DA1) has at least two cyclic structures having a phenolic hydroxyl group, and further has a specific structure linking them, and the resin satisfies a condition that a content of a fluorine element in the structure of the resin is 10,000 ppm by mass or less.

[Figure 1]